

ABSTRACT OF THE DISCLOSURE

A semiconductor device and a method of making a semiconductor device are provided, wherein the device includes
5 a die-pad, a semiconductor chip and a sealing resin. The die-pad has a first surface and a second surface opposite to the first surface. The second surface includes an exposed portion and a retreated portion around the exposed portion. The semiconductor chip is mounted on the first surface of the die-pad.
10 The sealing resin covers the die-pad and the semiconductor chip, exposes the exposed portion, and is held in contact with the retreated portion.